Advanced Packaging Update:
Market and Technology Trends

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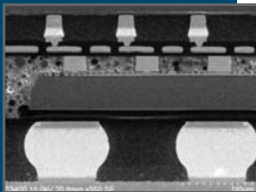

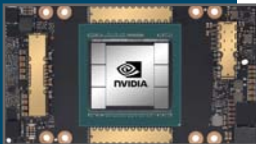

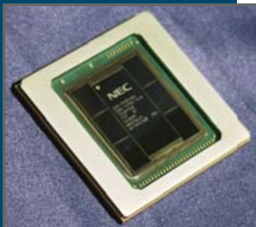

This issue of the Advanced Packaging Update covers OSAT financials for the first half of 2020. An update on the developments in 3D memory, including high bandwidth memory and hybrid bonding, is included. Package options for HBM plus logic are discussed, including silicon interposer, fan-out on substrate, embedded bridge, and organic interposer. A special section covers thermal concerns and solutions for mobile and high-performance applications, including integrated photonics. The substrate shortage is addressed including an analysis of the time to qualify new vendors and the status at substrate providers.

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